

PATENT ASSIGNMENT

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SUBMISSION TYPE:		NEW ASSIGNMENT	APPLICATION NUMBER 11/308839		
NATURE OF CONVEYANCE:		ASSIGNMENT OF ASSIGNOR'S INTEREST			
CONVEYING PARTY DATA					
Name		Execution Date			
CHENG-TIEN LAI		2006-04-20			
ZHI-YONG ZHOU		2006-04-20			
QIAO-LI DING		2006-04-20			
RECEIVING PARTY DATA					
Name	Street Address	Internal Address	City	State/Country	Postal Code
Foxconn Technology Co., Ltd.	3-2,CHUNG SHAN ROAD		TU CHENG	TAIWAN	
CORRESPONDENCE DATA					
FAX NUMBER: 7147384649					
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>					
When the customer number has been provided, the Office of Public Records will obtain the correspondence data from the official record on file at the USPTO.					
CUSTOMER NUMBER: 054000					
NAME OF PERSON SIGNING:		Jeffrey T. Knapp			
DATE SIGNED:		2006-05-12			
Total Attachments: 2 source=US9993assign1.tif source=US9993assign2.tif					

CH \$40.00 503789 11308839

ASSIGNMENT

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

- | | | | |
|----|----------------|---------------|------------------|
| 1. | Cheng-Tien Lai | , residing at | Tu-Cheng, Taiwan |
| 2. | Zhi-Yong Zhou | , residing at | Shenzhen, China |
| 3. | Qiao-Li Ding | , residing at | Shenzhen, China |
| 4. | | , residing at | |
| 5. | | , residing at | |
| 6. | | , residing at | |
| 7. | | , residing at | |
| 8. | | , residing at | |

hereby sell(s), assign(s) and transfer(s) unto: Foxconn Technology Co.,Ltd, having a principal place of business at 3-2, Chung Shan Road, Tu-cheng City, Taipei Hsien, Taiwan, ROC hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as Memory Module Assembly Including A Clamp For Mounting Heat Sinks Thereon for which the undersigned

[] previously executed --- Ser. No. _____ and filing date of _____
[x] is executing concurrently herewith

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE's full protection and title in and to the invention hereby transferred.

1. Cheng-Tien Lai
Cheng-Tien Lai inventor

Apr. 20, 2006
Date

Witness

2. Zhi-Yong Zhou
Zhi-Yong Zhou inventor

Apr. 20, 2006
Date

Witness

3. Qiao-Li Ding
Qiao-Li Ding inventor

Apr. 20, 2006
Date

Witness

4. _____
inventor

Date

Witness

5. _____
inventor

Date

Witness

6. _____
inventor

Date

Witness

7. _____
inventor

Date

Witness

8. _____
inventor

Date

Witness